



Call for Papers for the Annual Review of Electronic Design, Vol. 1

The International Engineering Consortium (IEC) is preparing the first volume of its *Annual Review of Electronic Design*, aimed mostly at electronic and semiconductor engineers. This publication will focus on relevant issues and challenges often faced in the engineering sector, all while emphasizing the new methods and technologies that have come about in the past year. This will present the crucial perspectives and experiences of industry leaders and will surely become a useful resource for corporate libraries, training programs, and individual study.

The IEC invites engineering professionals to submit papers for possible publication in *Volume 1* of the *Annual Review of Electronic Design*, slated for publication in December 2007. These papers should treat subjects related to application-specific and chip level functional design; PCB and package technologies; cable and fiber interconnect design; high-speed timing, jitter, and noise; signal processing, equalization, and coding; passive component characterization and modeling; power integrity and power-aware design; electromagnetic compatibility and interference; and text fixturing and measurement methodology.

Authors may also consider the current and potential markets in these areas, the business models adoptable by companies, pricing and fee structures, regulatory and standards issues, etc. Global case studies will be considered if they are non-promotional and written by the participating company or organization.

All submitted papers are reviewed in-house to determine acceptance for publication. Although a general discussion of particular engineering applications and products is permissible, papers should be *noncommercial* in nature and should *not* focus on specific brand-name products or solutions.

The submission deadline for the *Annual Review of Electronic Design, Vol. 1* is **Thursday, May 31, 2007**. Please submit your paper via e-mail to the following address: asulluchuco@iec.org.

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All contributing authors will receive a complimentary copy of the final publication.

Submission Guidelines

1. Papers should be between five and 20 pages (approximately 2,500 to 10,000 words) in length and *noncommercial*. Include each author's name, title, and organization. Submit only a complete, *final* version of the paper (no drafts, excerpts, or works in progress).
2. An electronic copy of the paper in *MS Word format* must be submitted via e-mail to asulluchuco@iec.org.
3. Please save the text and any accompanying graphics (figure, tables, charts, etc.) as separate files. Be sure to reference in the text where those graphics should be placed.
4. All text within figures, tables, charts, etc. should be clearly printed in a sans-serif font (e.g., Arial, Helvetica) and in a size that is large enough to be read easily.
5. Graphics should be high-resolution JPEG, TIFF, EPS, PowerPoint, or Excel files. NOTE: All graphics are published in black and white (grayscale) only.